

Application Serial No: 10/552,301  
Responsive to the Office Action mailed on: July 10, 2008

### REMARKS

This Amendment is in response to the Office Action mailed on July 10, 2008. Claims 1 and 5 are amended. Claims 1 and 5 are amended editorially and are supported, for example, in the specification at page 5, lines 21-24 and in Figures 1 and 2. No new matter is added. Claims 1 and 4-7 are pending.

#### §102 Rejections:

Claims 1 and 4-7 are rejected as being anticipated by Toshihiro (JP 08-064401). This rejection is traversed.

Claim 1 is directed to a chip resistor that requires, among other features, a chip-shaped resistor element made of metal, and at least two electrodes provided on a flat electrode forming surface of the resistor element.

Toshihiro does not disclose or suggest these features. Toshihiro is directed to a chip-like electronic part that includes a resistor layer (4), a ceramic substrate (1), electrode layers (2, 3 and 6) and an insulation layer (8) separated from the resistor layer (4) (see Abstract). The rejection interprets the ceramic substrate of (1) of Toshihiro as the electrode forming surface and the resistor layer (4) as the resistor element of claim 1. However, the ceramic substrate (1) is separate from the resistor layer (4) and by definition is not made of metal. Thus, the ceramic substrate (1) cannot be the flat electrode forming surface of a resistor element, as required by claim 1. Moreover, Toshihiro only discloses the electrodes (2, 3 and 6) on each of the surfaces of the ceramic substrate (1) and not on a flat electrode forming surface of the resistor layer (4), as required by the resistor element of claim 1. Thus, nowhere does Toshihiro disclose or suggest at least two electrodes provided on a flat surface of a resistor element, as required by claim 1. For at least these reasons claim 1 is not suggested by Toshihiro and should be allowed. Claim 4 depends from claim 1 and should be allowed for at least the same reasons.

Claim 5 is directed to a method for manufacturing a chip resistor that requires, inter alia, forming a plurality of insulating layers on an electrode-forming surface of a plate-shaped resistor element material made of metal.

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Toshihiro does not disclose or suggest these features. Figure 1(a) of Toshihiro discloses that the insulating layer (8) is formed on a surface of the ceramic substrate (1). As discussed above, the ceramic substrate (1) of Toshihiro cannot be an electrode forming surface of a resistor element. Accordingly, Toshihiro also cannot disclose or suggest forming the insulating layer (8) on an electrode-forming surface of the resistor layer (4), as required by claim 5. For at least these reasons claim 5 is not suggested by Toshihiro and should be allowed. Claims 6 and 7 depend from claim 1 and should be allowed for at least the same reasons.

Conclusion:

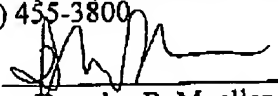
Applicant respectfully asserts that claims 1 and 4-7 are in condition for allowance. If a telephone conference would be helpful in resolving any issues concerning this communication, please contact Applicant's primary attorney-of record, Douglas P. Mueller (Reg. No. 30,300), at (612) 455-3804.



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Respectfully submitted,

HAMRE, SCHUMANN, MUELLER &  
LARSON, P.C.  
P.O. Box 2902  
Minneapolis, MN 55402-0902  
(612) 455-3800

By:   
Douglas P. Mueller  
Reg. No. 30,300  
DPM/ahk